CLAIMS

1. A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a core substrate and electric connection is achieved through via holes,

the thickness of conductive layer on said core substrate being larger than the thickness of the conductive layer on interlayer insulation layer, and

the side face of the conductive layer on said core substrate being tapered and when it is assumed that an angle formed by a straight line connecting the top end and bottom end of the side face of the conductive layer and the horizontal face of the core substrate is Θ, said Θ satisfying a relational equation of $2.8 < \tan\Theta < 55$.

2. The multilayer printed wiring board according to claim 1 wherein assuming that the thickness of the conductive layer on said core substrate is $\alpha 1$ and the thickness of the conductive layer on the interlayer insulation layer is $\alpha 2$, a relation of $\alpha 2 < \alpha 1 \leq 40\alpha 2$ exists.

3. The multilayer printed wiring board according to any one of claims 1 wherein said $\alpha 1$ is in the relation of $1.2\alpha 2 \leq \alpha 1 \leq 40\alpha 2$.

4. The multilayer printed wiring board according to any one of claims 1-3 wherein the conductive layer on the front and rear surfaces of said core substrate is a conductive layer for power source or a conductive layer for grounding.

5. The multilayer printed wiring board according to any one of claims 1-4 wherein a capacitor is loaded on the surface thereof.

6. A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a core substrate and electric connection is achieved through via holes,

said core substrate being a multilayer core substrate composed of three or more layers, having the conductive layers on the front and rear surfaces and a thick conductive layer in the inner layer, and

of the conductive layer in the inner layer of said core substrate and the conductive layers on the front and rear surfaces, at least a layer is a conductive layer for power source or a conductive layer for grounding.

7. A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a core substrate and electric connection is achieved through via holes,

said core substrate being a mutilayer core substrate composed of three or more layers, having the conductive layers on the front and rear surfaces and a thick

conductive layer in the inner layer, and

of the conductive layers in the inner layer of said core substrate, at least a layer being a conductive layer for power source or a conductive layer for grounding and at least a layer of those on the front and rear surfaces being composed of a signal line.

8. The multilayer printed wiring board according to claim 6 or 7 wherein the thickness of the conductive layer in the inner layer of said core substrate is larger than the thickness of the conductive layer on the interlayer insulation layer.

9. The multilayer printed wiring board according to any one of claims 6-8 wherein the conductive layer in the inner layer of said core substrate is composed of two layers or more.

10. The multilayer printed wiring board according to any one of claims 6-9 wherein in said core substrate, the conductive layers of said inner layer are formed via resin layer on both surfaces of a metal plate isolated electrically and said conductive layers on the front and rear surfaces are formed via resin layer outside the conductive layer in the inner layer.

11. The multilayer printed wiring board according to any one of claims 6-10 wherein said core substrate includes a thick conductive layer in the inner layer and a thin conductive layers in a surface layer.

12. The multilayer printed wiring board according to any one of claims 6-11 wherein each conductive layer of the inner layer of said core substrate is a conductive layer for power source or a conductive layer for grounding.

13. The multilayer printed wiring board according to any one of claims 6, 8-12 wherein the conductive layer on the front surface of said core substrate is a conductive layer for power source or a conductive layer for grounding, and the conductive layer on the rear surface is a conductive layer for power source or a conductive layer for grounding.

14. The multilayer printed wiring board according to any one of claims 6-13 wherein said conductive layer for power source and said conductive layer for grounding are disposed alternately.

15. The multilayer printed wiring board according to any one of claims 6-14 in which the side face of the conductive layer in the inner layer of said core substrate or/and

the side face of the conductive layer on the front surface are tapered and when it is assumed that an angle formed by a straight line connecting the top end and

bottom end of the side face of the conductive layer and the horizontal face of the core substrate is Θ, said Θ satisfies a relational equation of $2.8 < \tan\Theta < 55$.

16. The multilayer printed wiring board according to any one of claims 6-15 wherein assuming that the sum of the thickness of the conductive layer for power source on the front layer of said core substrate and the thickness of the conductive layer for power source in the inner layer is $\alpha 1$ and the thickness of the conductive layer on the interlayer insulation layer is $\alpha 2$, a relation of $\alpha 2 < \alpha 1 \leq 40\alpha 2$ exists.

17. The multilayer printed wiring board according to any one of claims 6-15 wherein assuming that the sum of the thickness of the conductive layer for grounding on the front layer of said core substrate and the thickness of the conductive layer for grounding in the inner layer is $\alpha 1$ and the thickness of the conductive layer on the interlayer insulation layer is $\alpha 2$, a relation of $\alpha 2 < \alpha 1 \leq 40\alpha 2$ exists.

18. The multilayer printed wiring board according to any one of claims 6-15 wherein assuming that the sum of the thickness of the conductive layer for power source on the front layer of said core substrate and the thickness of the conductive layer for power source in the inner layer is $\alpha 1$ and the thickness of the conductive layer on the interlayer insulation layer is $\alpha 2$, the relation of $\alpha 2 < \alpha 1 \leq 40\alpha 2$, and

assuming that the sum of the thickness of the conductive layer for grounding on the front layer of said core substrate and the thickness of the conductive layer for grounding in the inner layer is $\alpha 3a$ and the thickness of the conductive layer on the interlayer insulation layer is $\alpha 2$, the relation of $\alpha 2 < \alpha 3 \leq 40\alpha 2$ exists.